24-Stage Frequency Divider

The MC14521B consists of a chain of 24 flip–flops with an input circuit that allows three modes of operation. The input will function as a crystal oscillator, an RC oscillator, or as an input buffer for an external oscillator. Each flip–flop divides the frequency of the previous flip–flop by two, consequently this part will count up to $2^{24} = 16,777,216$. The count advances on the negative going edge of the clock. The outputs of the last seven–stages are available for added flexibility.

- All Stages are Resettable
- Reset Disables the RC Oscillator for Low Standby Power Drain
- RC and Crystal Oscillator Outputs Are Capable of Driving External Loads
- Test Mode to Reduce Test Time
- V_{DD}' and V_{SS}' Pins Brought Out on Crystal Oscillator Inverter to Allow the Connection of External Resistors for Low–Power Operation
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load over the Rated Temperature Range.

MAXIMUM RATINGS (Voltages Referenced to V_{SS}) (Note 2.)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 3.)	500	mW
T _A	Ambient Temperature Range	Temperature Range -55 to +125	
T _{stg}	Storage Temperature Range	e Range -65 to +150	
TL	Lead Temperature (8–Second Soldering)	260	°C

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \ or \ V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648



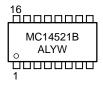


SOIC-16 D SUFFIX CASE 751B





SOEIAJ-16 F SUFFIX CASE 966



A = Assembly Location WL, L = Wafer Lot

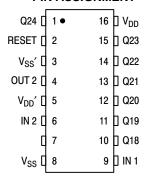
YY, Y = Year WW, W = Work Week

ORDERING INFORMATION

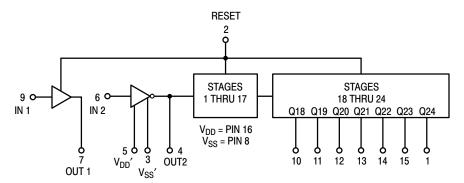
Device	Package	Shipping
MC14521BCP	PDIP-16	2000/Box
MC14521BD	SOIC-16	48/Rail
MC14521BDR2	SOIC-16	2500/Tape & Reel
MC14521BF	SOEIAJ-16	See Note 1.
MC14521BFEL	SOEIAJ-16	See Note 1.
MC14521BFR2	SOEIAJ-16	See Note 1.

 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

PIN ASSIGNMENT



BLOCK DIAGRAM



Output	Count Capacity
Q18	$2^{18} = 262,144$
Q19	$2^{19} = 524,288$
Q20	$2^{20} = 1,048,576$
Q21	$2^{21} = 2,097,152$
Q22	$2^{22} = 4,194,304$
Q23	$2^{23} = 8,388,608$
Q24	$2^{24} = 16,777,216$

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

		V _{DD}	- 5	5°C		25°C		125	5°C	
Characteristic	Symbol	Vdc	Min	Max	Min	Тур (4.)	Max	Min	Max	Unit
Output Voltage "0" Level $V_{in} = V_{DD}$ or 0	V _{OL}	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or V_{DD} "1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage "0" Level (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	V _{IL}	5.0 10 15	_ _ _	1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0	_ _ _	1.5 3.0 4.0	Vdc
"1" Level $(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	V _{IH}	5.0 10 15	3.5 7.0 11		3.5 7.0 11	2.75 5.50 8.25		3.5 7.0 11		Vdc
	ІОН	5.0 5.0 10 15	- 1.2 - 0.25 - 0.62 - 1.8	1111	- 1.0 - 0.2 - 0.5 - 1.5	- 1.7 - 0.36 - 0.9 - 3.5	_ _ _ _	- 0.7 - 0.14 - 0.35 - 1.1	_ _ _	mAdc
		5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8		- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ Sink $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	I _{OL}	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8		0.36 0.9 2.4	_ _ _	mAdc
Input Current	I _{in}	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)	I _{DD}	5.0 10 15	_ _ _	5.0 10 20	_ _ _	0.005 0.010 0.015	5.0 10 20	_ _ _	150 300 600	μAdc
Total Supply Current ^(5.) ^(6.) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	I _T	5.0 10 15			$I_{T} = (0$.42 μA/kHz) .85 μA/kHz) .40 μA/kHz)	f + I _{DD}			μAdc

^{4.} Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
5. The formulas given are for the typical characteristics only at 25°C.
6. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.003.

SWITCHING CHARACTERISTICS (7.) $(C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C})$

Characteristic	Symbol	V _{DD} Vdc	Min	Typ ^(8.)	Max	Unit
Output Rise and Fall Time (Counter Outputs) $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_{L} + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns}$	t _{TLH} , t _{THL}	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q18 $t_{PHL}, t_{PLH} = (1.7 \text{ ns/pF}) \text{ C}_{L} + 4415 \text{ ns} \\ t_{PHL}, t_{PLH} = (0.66 \text{ ns/pF}) \text{ C}_{L} + 1667 \text{ ns} \\ t_{PHL}, t_{PLH} = (0.5 \text{ ns/pF}) \text{ C}_{L} + 1275 \text{ ns}$	t _{PHL} , t _{PLH}	5.0 10 15	_ _ _	4.5 1.7 1.3	9.0 3.5 2.7	μѕ
Clock to Q24 t_{PHL} , t_{PLH} = (1.7 ns/pF) C_L + 5915 ns t_{PHL} , t_{PLH} = (0.66 ns/pF) C_L + 2167 ns t_{PHL} , t_{PLH} = (0.5 ns/pF) C_L + 1675 ns		5.0 10 15	_ _ _	6.0 2.2 1.7	12 4.5 3.5	
Propagation Delay Time Reset to Q_n $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 1215 \text{ ns}$ $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 467 \text{ ns}$ $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 350 \text{ ns}$	t _{PHL}	5.0 10 15	_ _ _	1300 500 375	2600 1000 750	ns
Clock Pulse Width	t _{WH(cl)}	5.0 10 15	385 150 120	140 55 40	_ _ _	ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	_ _ _	3.5 9.0 12	2.0 5.0 6.5	MHz
Clock Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15	 _ _	_ _ _	15 5.0 4.0	μѕ
Reset Pulse Width	t _{WH(R)}	5.0 10 15	1400 600 450	700 300 225	_ _ _	ns
Reset Removal Time	t _{rem}	5.0 10 15	30 0 - 40	- 200 - 160 - 110	_ _ _	ns

- 7. The formulas given are for the typical characteristics only at 25°C.
 8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

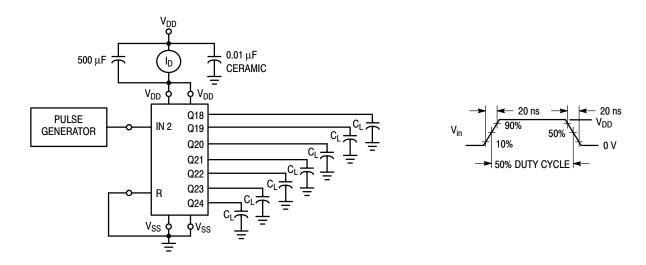


Figure 1. Power Dissipation Test Circuit and Waveform

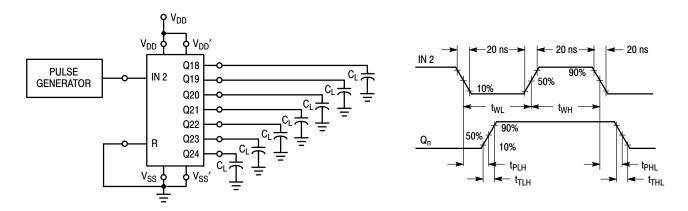
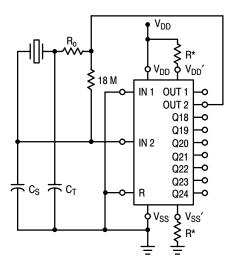


Figure 2. Switching Time Test Circuit and Waveforms



^{*} Optional for low power operation, $10 \text{ k}\Omega \leq R \leq 70 \text{ k}\Omega$.

Figure 3. Crystal Oscillator Circuit

Characteristic	500 kHz Circuit	50 kHz Circuit	Unit
Crystal Characteristics Resonant Frequency Equivalent Resistance, R _S	500	50	kHz
	1.0	6.2	kΩ
External Resistor/Capacitor Values R _o C _T C _S	47	750	kΩ
	82	82	pF
	20	20	pF
Frequency Stability Frequency Change as a Function of V_{DD} ($T_A = 25^{\circ}$ C) V_{DD} Change from 5.0 V to 10 V V_{DD} Change from 10 V to 15 V Frequency Change as a Function of Temperature ($V_{DD} = 10 \text{ V}$) T_A Change from -55° C to $+25^{\circ}$ C	+ 6.0 + 2.0 - 4.0	+ 2.0 + 2.0 - 2.0	ppm ppm
MC14521 only Complete Oscillator* T _A Change from +25°C to+125°C	+ 100	+ 120	ppm
MC14521 only	- 2.0	- 2.0	ppm
Complete Oscillator*	- 160	- 560	ppm

^{*}Complete oscillator includes crystal, capacitors, and resistors.

Figure 4. Typical Data for Crystal Oscillator Circuit

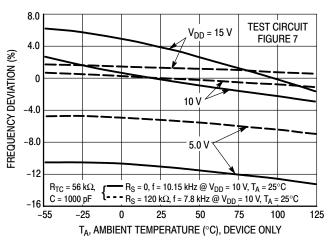


Figure 5. RC Oscillator Stability

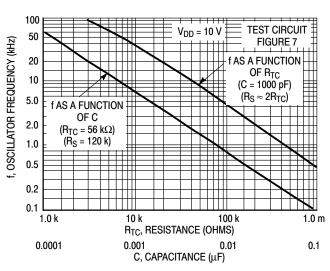


Figure 6. RC Oscillator Frequency as a Function of R_{TC} and C

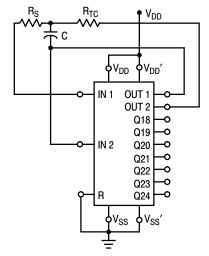


Figure 7. RC Oscillator Circuit

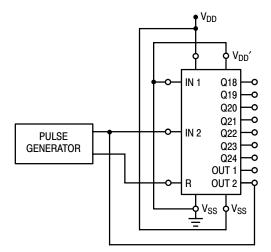
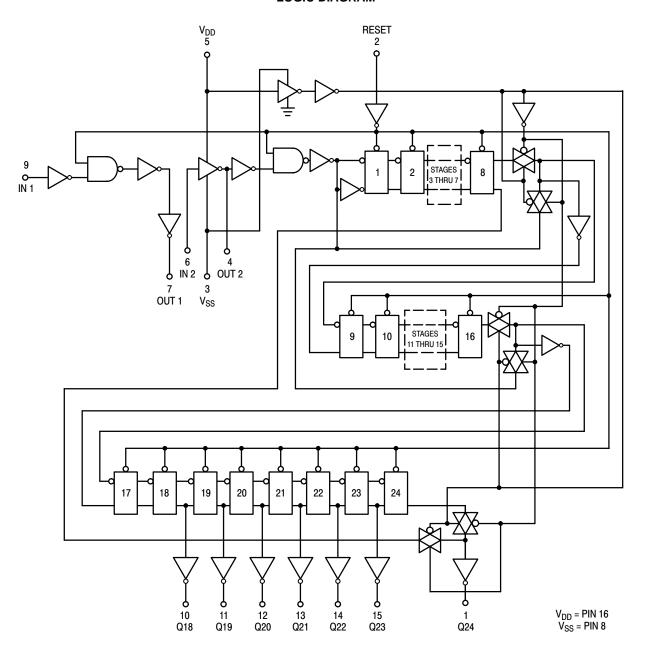


Figure 8. Functional Test Circuit

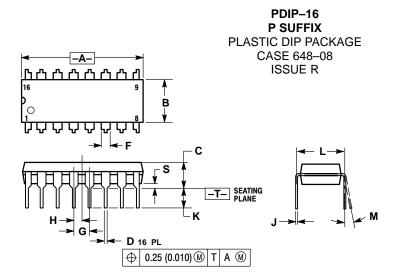
FUNCTIONAL TEST SEQUENCE

	Inp	uts		0	utputs		Comments
	Reset	ln 2	Out 2	V _{SS} ′	V _{DD} ′	Q18 thru Q24	Counter is in three 8–stage sections in parallel mode Counter is reset. In 2 and
	1	0	0	V _{DD}	Gnd 	0	Out 2 are connected together
A test function (see Figure 8) has been included for the reduction of test time required to	0	1	1				First "0" to "1" transition on In 2, Out 2 node.
exercise all 24 counter stages. This test function		0	0				255 "0" to "1" transitions
divides the counter into three 8-stage sections, and 255 counts are loaded in each of the		_	_				are clocked into this In 2, Out 2 node.
8-stage sections in parallel. All flip-flops are now at a logic "1". The counter is now returned		_	_				
to the normal 24–stages in series configuration. One more pulse is entered into Input 2 (In 2)		1	1			1	The 255th "0" to "1" transition.
which will cause the counter to ripple from an all "1" state to an all "0" state.		0	0			1	
		1	0	Gnd	V _{DD}	1	Counter converted back to 24–stages in series mode.
		1	0			1	Out 2 converts back to an output.
	•	0	1	V		0	Counter ripples from an all "1" state to an all "0" stage.

LOGIC DIAGRAM



PACKAGE DIMENSIONS

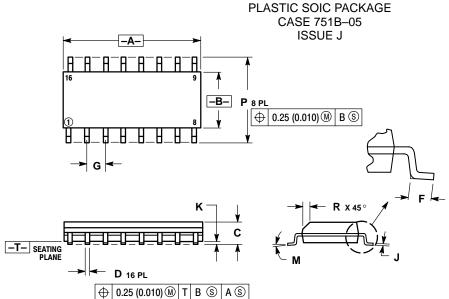


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10 °
S	0.020	0.040	0.51	1.01

PACKAGE DIMENSIONS

SOIC-16 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751B-05



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI

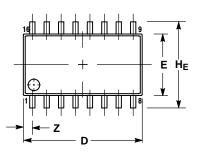
- DIMENSIONING AND TOLERANCING PER ANS Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOILD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

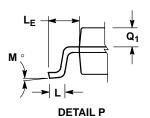
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

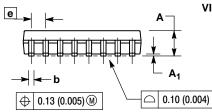
PACKAGE DIMENSIONS

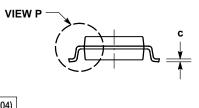
SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE

CASE 966-01 **ISSUE O**









NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- 1. DIMENSIONING AND TOLERANGING FEB 2005
 714.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE
 MOLD FLASH OR PROTRUSIONS AND ARE
 MEASURED AT THE PARTING LINE. MOLD FLASH
 OR PROTRUSIONS SHALL NOT EXCEED 0.15
- OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Ε	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

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